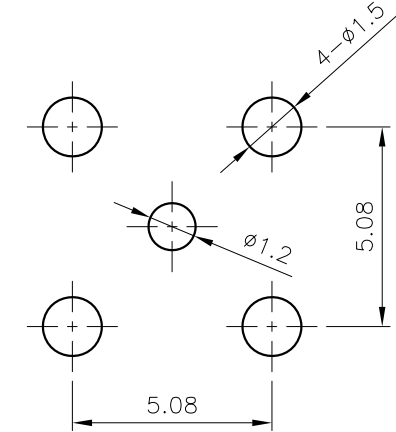
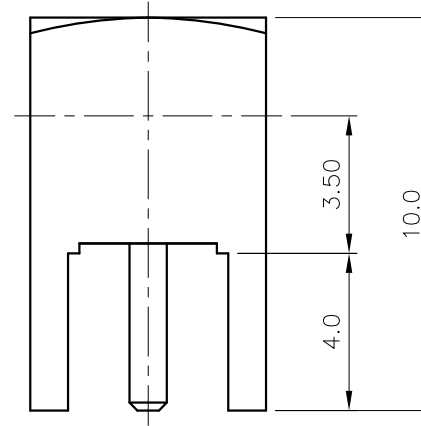
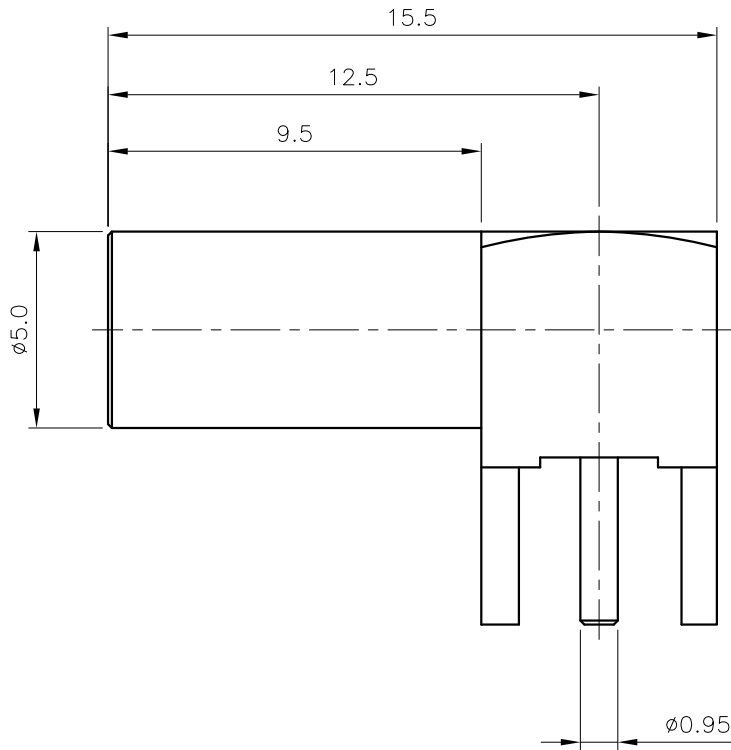


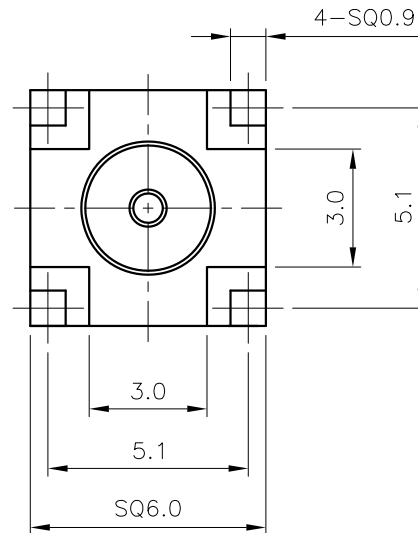
REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	S.H.KIM		2023.01.12.

■ 조립순서

1. ②번 원형 바디에 ④번 절연체를 조립한다.
2. 1번 조립품에 ③번 밴딩핀을 조립한다.
3. 2번까지 조립된 원형 바디에 밴딩핀을 ①번 사각 바디에 맞게 돌려 끼워넣고 바디를 억지끼운다.
4. ⑤번 절연체를 방향에 맞게 핀에 넣고 조립한다.



PCB MOUNTING HOLE SIZE



5	INSULATOR	1	TEFLON		DIN03221-N/2
4	INSULATOR	1	TEFLON		DIN03227-N/2
3	CONTACT	1	BeCu C17300	Gold Plate	DCT04356-5/1
2	JACK BODY	1	MBsBD C3604BD-F	Gold Plate	DBD04882-5/1
1	사각 BODY	1	MBsBD C3604BD-F	Gold Plate	DBD04881-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal ±0.1	DATE 2023. 01. 12.			 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017		
	Angle ±1°	APPROVED BY					
MATERIAL _____		CHECKED BY			TITLE MCX50 PCB JL-4R		
		DRAWN BY S.H.KIM					
FINISH _____		SCALE 5/1	UNIT mm		A4	DWG NO. CN04089-7/1	
					REVISION	I R	SHEET 1 of 1